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BIB DATA SHEET

CONFIRMATION NO. 9500

| APPLICANTS APPLICANTS Kilyoshi Ool, Nagano-shi, JAPAN; Yasuyoshi Horikawa, Nagano-shi, JAPAN; Yasuyoshi Horikawa, Nagano-shi, JAPAN; Yasuyoshi Horikawa, Nagano-shi, JAPAN; Yasuyoshi Horikawa, Nagano-shi, JAPAN; **CONTINUING DATA **FOREIGN APPLICATIONS JAPAN 2003-104070 04/08/2003 **I FEGUIRED, FOREIGN FILING LICENSE GRANTED ** 06/08/2004 **Foreign Pricity claimed | CONFIRMATION NO. 9500 | | | | | | | | | | | |
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| RULE APPLICANTS Kiyoshi Ool, Nagano-shi, JAPAN; Yasuyoshi Horikawa, Nagano-shi, JAPAN; Akio Rokugawa, Nagano-shi, JAPAN; ***CONTINUING DATA ****FOREIGN APPLICATIONS JAPAN 2003-104070 04/08/2003 ***IF REQUIRED, FOREIGN FILING LICENSE GRANTED *** 06/08/2004 Foreign Priority claimed SUSS 119(a-q) conditions met May yes | | DATE | | | | | | | | | | |
| APPLICANTS Kiyoshi Oci, Nagano-shi, JAPAN; Yasuyoshi Horikawa, Nagano-shi, JAPAN; Akio Rokugawa, Nagano-shi, JAPAN; ***CONTINUING DATA**** ***FOREIGN APPLICATIONS**** JAPAN 2003-104070 04/08/2003 ***IF REQUIRED, FOREIGN FILING LICENSE GRANTED *** 06/08/2004 Foreign Priority dalimed | 10/011,70 | 00/20/2001 | | | 237 | | 2091 | | | CU-3664 HJS | | |
| Akio Řokugawa, Nagano-shi, JAPAN; "CONTINUING DATA """ "FOREIGN APPLICATIONS "" JAPAN 2003-104070 04/08/2003 "IF REQUIRED, FOREIGN FILING LICENSE GRANTED "" 06/08/2004 Foreign Priority dailmed | APPLICANTS Kiyoshi Ool, Nagano-shi, JAPAN; | | | | | | | | | | | |
| ** FOREIGN APPLICATIONS JAPAN 2003-1040/70 04/08/2003 *** IF REQUIRED, FOREIGN FILING LICENSE GRANTED ** *** O6/08/2004 *** IF REQUIRED, FOREIGN FILING LICENSE GRANTED ** *** O6/08/2004 *** OF REGUN FILING LICENSE GRANTED ** *** OF REGUN FI | Akio Rokugawa, Nagano-shi, JAPAN; | | | | | | | | | | | |
| ## SPECEIVED # | | | | | | | | | | | | |
| GR/08/2004 Foreign Priority claimed Version No. STATE OR COUNTRY DRAWINGS CLAIMS SUSC 119(eq.4) conditions net Version No. No. SHEETS COUNTRY DRAWINGS CLAIMS 12 23 5 ADDRESS LADAS & PARRY LLP 244 SQUITH MICHIGAN AVENUE SUITE 1800 CHICAGO, IL 60604 UNITED STATES TITLE Semiconductor device substrate, semiconductor device, and manufacturing method thereof FILING FEE RECEIVED 996 FEES: Authority has been given in Paper No. Other Processing Ext. of time) To charge/credit DEPOSIT ACCOUNT No. Other Processing Ext. of time) 1.1.18 Fees (Fissue) 1.1.18 Fees (Issue) | | | | | | | | | | | | |
| Sc USC 119(a-d) conditions met | | | | | | | | | | | | |
| Varified and Accordanged ADURLAS M MENU/ Initiate JAPAN 12 23 5 | | | | | | | | | | INDEPENDENT | | |
| LADAS & PARRY LLP 224 SOUTH MICHIGAN AVENUE SUITE 1600 CHICAGO, IL 60604 UNITED STATES TITLE Semiconductor device substrate, semiconductor device, and manufacturing method thereof FILING FEE RECEIVED 996 FEES: Authority has been given in Paper No to charge/credit DEPOSIT ACCOUNT No for following: Call Fees Parry LLP | /erified and /DOUGLAS M MENZ/ | | | | DRA | | | | | | | |
| Semiconductor device substrate, semiconductor device, and manufacturing method thereof FILING FEE FEES: Authority has been given in Paper | LADAS & PARRY LLP 224 SOUTH MICHIGAN AVENUE SUITE 1600 CHICAGO, IL 60604 | | | | | | | | | | | |
| FILING FEE RECEIVED 996 FEES: Authority has been given in Paper No to charge/credit DEPOSIT ACCOUNT Of the following: Call Fees All Fees 1.16 Fees (Filling) 1.17 Fees (Processing Ext. of time) 1.18 Fees (Issue) 1.18 Fees (Iss | TITLE | | | | | | | | | | | |
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